form <b>PTO-1595</b> (Rev. 03-11) DMB No. 0651-0027 (exp. 03/31/2012)	U.S. DEPARTMENT OF COMMERCE United States Patent and Trademark Office
RECORDATION FOR PATENTS	
To the Director of the U.S. Patent and Trademark Office: Please	
Name of conveying party(les):	2. Name and address of receiving party(les)
Eiju Yamada (02/09/2012), Yoshinori Ohashi (02/17/2012), and Akihiko Kinoshita (02/10/2012)	Name: Sony Corporation Internal Address:
Additional name(\$) of conveying party(les) attached?	Street Address:
3. Nature of conveyance/Execution Date(s):  Execution Date(s): In parentheses after inventor name  X Assignment Merger Change of Name  Security Agreement Joint Research Agreement  Government Interest Assignment  Executive Order 9424, Confirmatory License  Other	1-7-1 Konan, Minato-ku Tokyo 108-0075 JAPAN  City: State: Country: Additional name(s) & address(es) attached?  Yes X No
4. Application or patent number(s):  A. Patent Application No.(s)  13/497,984  Additional numbers attached	This document is being filed together with a new application.  B. Patent No.(s)  Yes X No
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Bruno Polito LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
Internal Address: Atty. Dkt.: SONYJP 3.3-2334 Street Address: 600 South Avenue West	Authorized to be charged to deposit account     Enclosed     None required (government interest not affecting title)
City: Westfield	8. Payment Information
State:         NJ         Zip:         07090           Phone Number:         908-654-5000           Fax Number:         908-654-7866           Email Address:         ataylor@ldlkm.com	Deposit Account Number 12-1095  Authorized User Name Bruno Polito
9. Signature:	
Signature	March 23, 2012
Bruno Polito - 38,580	Total number of pages including cover aheat, attachments, and documents:

1655872

PATENT REEL: 027932 FRAME: 0409

## Docket No.: Sony Ref. No.: SP248027US00

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD, AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 13/497,984; Filing Date: March 23, 2012

This assignment executed on the dates indicated below.

Eiju YAMADA	
Name of First or Sole Inventor	Execution Date of U.S. Patent Application
Kanagawa, Japan	
Residence of First or Sole Inventor	•
Signature of First or Sole Inventor	February 9, 2012
Signature of First or Sole Inventor	Date of this Assignment
SP248027US00_20120131_Assignment[1].DOC	<del>-</del>

PATENT REEL: 027932 FRAME: 0410

Docket No.: Sony Ref. No.: SP248027US00

Yoshinori OHASHI	
Name of Second Joint Inventor	Execution Date of U.S. Patent Application
Tokyo, Japan	
Residence of Second Joint Inventor	
Signature of Second Joint Inventor	February 17, 2012
Signature of Second Joint Inventor	Date of this Assignment
Akihiko KINOSHITA	
Name of Third Joint Inventor	Execution Date of U.S. Patent Application
Tokyo, Japan	
Residence of Third Joint Inventor	
Akihiko kinostrita	February 10, 2-0/2
Signature of Third Joint Inventor	Date of this Assignment

LDLKM

**RECORDED: 03/23/2012**